

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	868145	(package packaging packaged)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 16:12
L2	3495904	(die chip ic (integrated adj circuit) semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 16:13
L3	180993	(stack stacking level stacked stackable) with (dice die chip ic (integrated adj circuit) semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 16:14
L4	14996	3 same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 16:14
L5	6747	4 same (substrate carrier pcb ((printed circuit wiring) adj4 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 16:16
L6	722	5 same (encapsulation encapsulate encasulating encapsulated encase enclosed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 16:16